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# Electrical contacts: A voltage scale for thermal runaway and issues in measurements of constriction resistance

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#### **Outline**

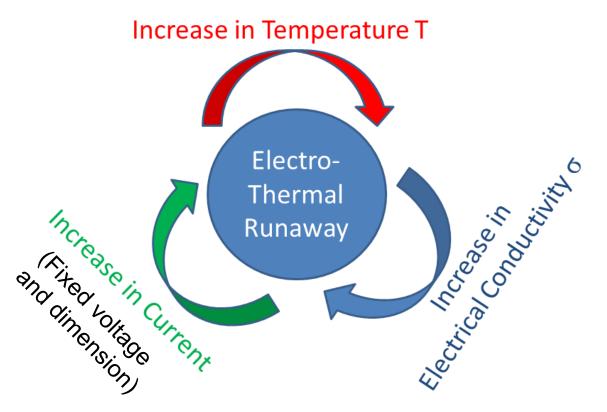
- Introduction
- Voltage scale for Electro-Thermal runaway
- Issues on experimental measurement of constriction resistance
- Conclusions and future works

#### Introduction

 Contact problems account for 40 percent of all electrical/electronic failures

- Severe heating due to local current constrictions at thin film contacts [1-3] and at bulk contacts [2,4] is also a concern to high power microwave sources, pulsed power systems, field emitters, thin film devices and integrated circuits, and interconnects, etc.
- 1. P. Zhang, Y. Y. Lau, and R. S. Timsit, IEEE Trans. Electron Devices **59**, 1936 (2012).
- 2. P. Zhang, doctoral dissertation, University of Michigan, Ann Arbor (2012).
- 3. P. Zhang, D. Hung, and Y. Y. Lau, J. Phys. D: Appl. Phys. **46**, 065502 (2013); Corrigendum, ibid, 46, 209501 (2013).
- 4. P. Zhang and Y. Y. Lau, IEEE J. Electron<sup>3</sup>Dev. Soc. 1, 83 (2013).

#### Electro-Thermal Runaway: A Positive Feedback



- •We investigate one aspect of electro-thermal instabilities, namely, the increase in electrical conductivity as the temperature increases, as typical of semiconductors.
- •This may lead to thermal runaway, at a fixed voltage.

$$C\frac{\partial T}{\partial t} = \kappa \frac{\partial^2 T}{\partial x^2} + J \cdot E$$

C: Heat capacity

T: Temperature

κ: Thermal conductivity

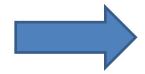
J: Current density

E: Electrical field



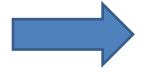
Assume electrical conductivity  $\sigma$  increases as temperature T increases, typical for semiconductors

$$\sigma(T) \approx \sigma_0 + \sigma_0 T$$



$$J \cdot E = \sigma(T)E^2 = (\sigma_0 + \sigma_0'T)E^2$$





$$C\frac{\partial T}{\partial t} = \kappa \frac{\partial^2 T}{\partial x^2} + (\sigma_0 + \sigma_0' T)E^2$$

Assume  $T \sim e^{jkx}$ 

$$C \frac{\partial T}{\partial t} - \left[\sigma_0' E^2 - \kappa k^2\right] T = \sigma_0 E^2$$



$$\frac{\partial T}{\partial t} - \left[ \frac{\sigma_0 'E^2 - \kappa k^2}{C} \right] T = \frac{\sigma_0}{C} E^2$$

If S > 0,  $T \sim e^{St}$ , i.e. thermal instability



$$S = \left\lceil \frac{\sigma_0' E^2 - \kappa k^2}{C} \right\rceil > 0$$



$$E > \sqrt{\frac{\kappa k^2}{\sigma_0}}$$

Multiply both sides by a length L

$$EL > (kL) \sqrt{\frac{\kappa}{\sigma_0}}$$



$$EL > (kL) \sqrt{\frac{\kappa}{\sigma_0'}} = (kL)V_s$$

There is a voltage scale V<sub>s</sub>, which characterizes thermal runaway

$$V_s = \sqrt{\frac{\kappa}{\sigma_0}}$$

 $\kappa$ : Thermal conductivity [W/(mK)]

 $\sigma_0$ ': Rate of change of the electrical conductivity with respect to temperature [1/( $\Omega$ mK)].

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$$V_s = \sqrt{rac{\kappa}{\sigma_0}}$$

Note:  $V_s$  depends only on material properties and is independent of geometry or the operating voltage. It measures the intrinsic tolerance of the material to electro-thermal instability.



	<i>κ</i> [W/(m-K)]	σ <sub>0</sub> ' [1/(Ω-m-K)]	V <sub>s</sub> [Volt]
Si	142	0.0012-0.7	14.2-348.9
Ge	58	0.0001-0.05	34-761.6
C (graphite)	127	$1.67 \times 10^{-4} - 8.33 \times 10^{-6}$	872.9-3903.8
SiC	370	4×10 <sup>-7</sup> or negative	3×10 <sup>4</sup>

SiC is the most resistant to thermal runaway for the same geometry and the same operating voltage, consistent with the well-known property of this material



### Experimental measurement of constriction resistance

$$R_{Total} = V/I$$

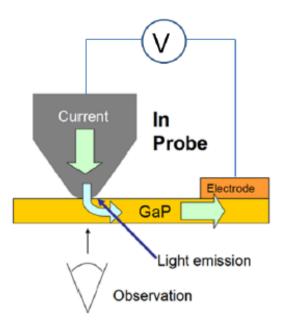
$$R_c = R_{Total} - R_{bulk}$$

How to accurately estimate R<sub>bulk</sub> is very important!

There is <u>arbitrariness</u> in the decomposition of  $R_{Total}$  into  $R_s$  and  $R_{bulk}$ 

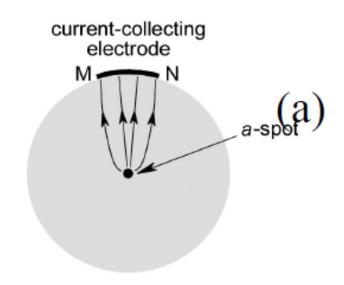


#### Experimental measurement of constriction resistance

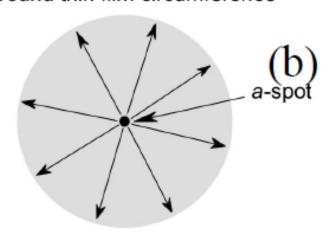


S. Sawada, et al, Proc. 58th IEEE Holm Conf. on Electrical Contacts, Portland, OR, 242 (2012).

- Case (a) greatly influences R<sub>bulk</sub> and also complicates its evaluation
- Model (b) underestimates  $R_{bulk}$  of case (a)



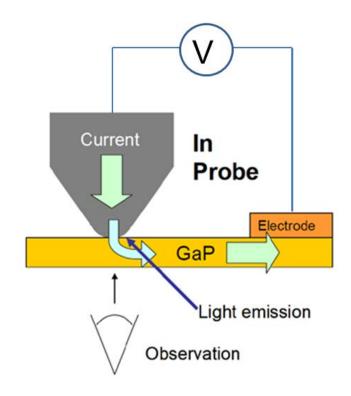
current collected uniformly around thin film circumference



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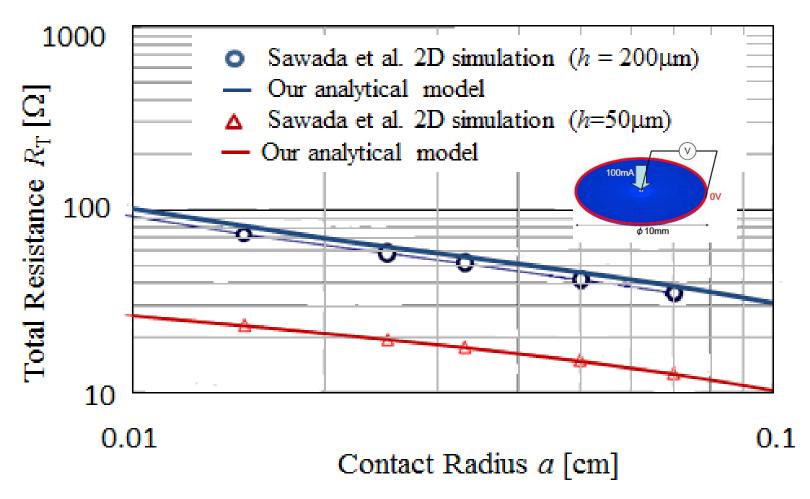
## Additional sources of uncertainty in two-terminal measurement

- Unavoidable contact resistance at the measuring electrodes
- Spreading resistance at the current collecting electrode



We have case (a) here

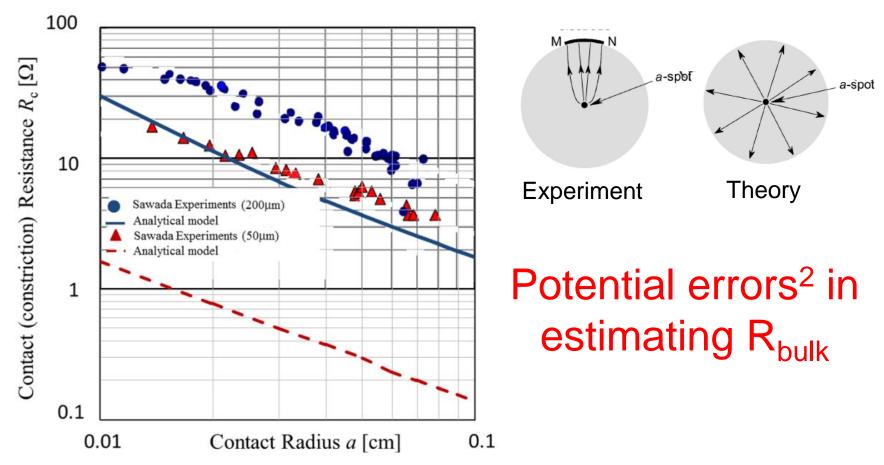
#### Theory vs. 2D cylindrical simulation



Good agreement due to same geometry used in simulation and theory

S. Sawada, et al, Proc. 58th IEEE Holm Conf. on Electrical Contacts, Portland, OR, 242 (2012).

### Theory vs. Experimental measurement of constriction resistance<sup>1</sup>



- <sup>1</sup>S. Sawada et al, Proc. 58th IEEE Holm Conf. on Electrical Contacts, Portland, OR, 242 (2012).
- <sup>2</sup>P. Zhang, Y. Y. Lau, R. S. Timsit, 59th IEEE Holm Conf. on Electrical Contacts, Newport, RI (2013).

#### Conclusions

- Made vast generalization in theory of electrical contact, for both bulk and thin-film contacts (applicable to high power microwave sources, field emitters, thin-film devices, MEMS, interconnects, etc).
- Voltage scaling developed for electro-thermal runaway.
- Issues in experimental measurement of constriction resistance are discussed.